MODIFYING MEMORY DEVICE ORGANIZATION IN HIGH DENSITY PACKAGES

ABSTRACT

A high density memory module is disclosed comprising a first packaged integrated circuit memory device having therein a first electrically insulating carrier and a first conductive routing pattern integral with said first carrier, and at least a first semiconductor circuit chip; a second packaged integrated circuit memory device electrically connected to said first device, wherein said first and second devices form a module; said second packaged integrated circuit device having therein a second electrically insulating carrier and second conductive routing pattern integral with said second carrier, and at least a second semiconductor circuit chip; and said second conductive routing pattern including means for modifying the architectural organization of said module.

Figure 1